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TITLE : METHOD AND APPARATUS FOR
 TESTING SOLDERABILITY OF
 ELECTRONIC COMPONENT

ABSTRACT : PURPOSE: To provide a method and an apparatus for testing solderability of an electronic part whereby a microgap is easily adjusted to a predetermined value and heating to predetermined temperatures is quickly and highly accurately achieved.

CONSTITUTION: The apparatus 10 for testing solderability of electronic components is provided with an external force detecting means 11 for supporting a component holding means 12 via a slide shaft mechanism 12b, a locking mechanism 12c capable of locking the slide shaft mechanism, a supporting member 14 for supporting a component bonding member 13 provided below the component holding means in a movable fashion in the vertical direction, and a solder bath 16 for accommodating a molten solder of constant temperatures which is supported below the supporting member to be movable up and down.

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